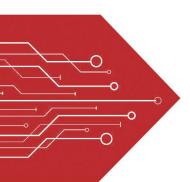
# MSKSEMI















**ESD** 

TVS

TSS

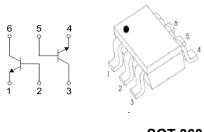
MOV

GDT

**PLED** 

# Broduct data sheet





**SOT-363** 

## **MMDT4401**

DUAL TRANSISTOR (NPN+NPN)

### **FEATURES**

- Epitaxial Planar Die Construction
- Ideal for Low Power Amplification and Switching

### MRKING:K2X

# Maximum Ratings (Ta = 25℃ unless otherwise specified)

Symbol	Parameter	Value	Units
V <sub>CBO</sub>	Collector-Base Voltage	60	<b>V</b>
V <sub>CEO</sub>	Collector-Emitter Voltage	40	<b>V</b>
V <sub>EBO</sub>	Emitter-Base Voltage	6	V
Ic	Collector Current -Continuous	0.6	Α
Pc	Collector Power Dissipation	0.2	W
R <sub>θJA</sub>	Thermal Resistance from Junction to Ambient	625	°C/W
TJ	Junction Temperature	150	°C
T <sub>stg</sub>	Storage Temperature	-55 to +150	$^{\circ}$

## NPN 4401 ELECTRICAL CHARACTERISTICS (Ta=25°C unless otherwise specified)

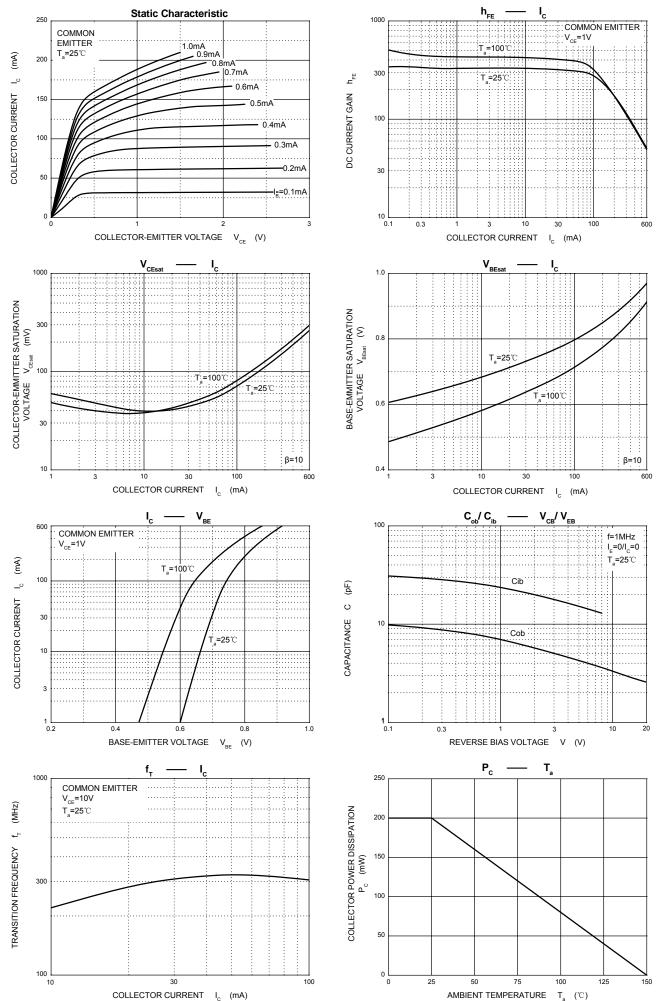
Parameter	Symbol	Test conditions		Max	Unit
Collector-base breakdown voltage	V <sub>(BR)CBO</sub>	I <sub>C</sub> = 100 μA, I <sub>E</sub> =0	60		V
Collector-emitter breakdown voltage	V <sub>(BR)CEO</sub>	I <sub>C</sub> = 1mA, I <sub>B</sub> =0	40		V
Emitter-base breakdown voltage	$V_{(BR)EBO}$	I <sub>E</sub> = 100 μA, I <sub>C</sub> =0	6		V
Collector cut-off current	I <sub>CBO</sub>	V <sub>CB</sub> = 50 V , I <sub>E</sub> =0		0.1	μΑ
Collector cut-off current	I <sub>CEO</sub>	V <sub>CE</sub> = 35 V , I <sub>B</sub> =0		0.5	μΑ
Emitter cut-off current	I <sub>EBO</sub>	V <sub>EB</sub> = 5V , I <sub>C</sub> =0		0.1	μΑ
	h <sub>FE(1)</sub>	V <sub>CE</sub> = 1V, I <sub>C</sub> = 0.1mA	20		
	h <sub>FE(2)</sub>	V <sub>CE</sub> = 1V, I <sub>C</sub> = 1mA	40		
DC current gain	h <sub>FE(3)</sub>	V <sub>CE</sub> = 1V, I <sub>C</sub> = 10mA	80		
	h <sub>FE(4)</sub>	V <sub>CE</sub> = 1V, I <sub>C</sub> = 150mA	100	300	
	h <sub>FE(5)</sub>	V <sub>CE</sub> = 2V, I <sub>C</sub> = 500mA	40		
Collector-emitter saturation voltage	V <sub>CE(sat)1</sub>	I <sub>C</sub> =150 mA, I <sub>B</sub> = 15mA		0.4	V
Collector-enlitter Saturation voltage	V <sub>CE(sat)2</sub>	I <sub>C</sub> =500 mA, I <sub>B</sub> = 50mA		0.75	<b>V</b>
Base-emitter saturation voltage	V <sub>BE(sat)1</sub>	I <sub>C</sub> = 150 mA, I <sub>B</sub> = 15mA	0.75	0.95	V
base-eiiiittei saturation voitage	V <sub>BE(sat)2</sub>	I <sub>C</sub> = 500 mA, I <sub>B</sub> = 50mA		1.2	<b>V</b>
Transition frequency	f <sub>T</sub>	V <sub>CE</sub> = 10V,I <sub>C</sub> = 20mA,f=100MHz	250		MHz
Output capacitance C <sub>c</sub>		V <sub>CB</sub> =5V, I <sub>E</sub> = 0,f=1MHz		6.5	pF
Delay time	t <sub>d</sub>	V <sub>CC</sub> =30V,		15	nS
Rise time	t <sub>r</sub>	V <sub>BE</sub> =2V,I <sub>C</sub> =150mA ,I <sub>B1</sub> =15mA		20	nS
Storage time	ts	V <sub>CC</sub> =30V, I <sub>C</sub> =150mA,I <sub>B1</sub> =-I <sub>B2</sub> =15mA		225	nS
Fall time	t <sub>f</sub>			30	nS



# **Typical Characteristics**

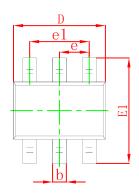


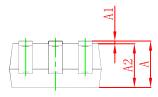


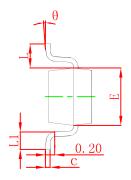




# **SOT-363 Package Outline Dimensions**

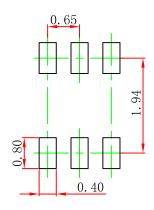






Symbol	Dimensions In Millimeters		Dimensions In Inches		
Syllibol	Min	Max	Min	Max	
Α	0.900	1.100	0.035	0.043	
A1	0.000	0.100	0.000	0.004	
A2	0.900	1.000	0.035	0.039	
b	0.150	0.350	0.006	0.014	
С	0.100	0.150	0.004	0.006	
D	2.000	2.200	0.079	0.087	
E	1.150	1.350	0.045	0.053	
E1	2.150	2.400	0.085	0.094	
е	0.650 TYP		0.026 TYP		
e1	1.200	1.400	0.047	0.055	
L	0.525 REF		0.021 REF		
L1	0.260	0.460	0.010	0.018	
θ	0°	8°	0°	8°	

# **SOT-363 Suggested Pad Layout**



#### Note:

- 1.Controlling dimension:in millimeters.
- 2.General tolerance:± 0.05mm.
- 3. The pad layout is for reference purposes only.

# **REEL SPECIFICATION**

P/N	PKG	QTY
MMDT4401	SOT-363	3000



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